

Bipolar Transistors Silicon NPN Epitaxial Type (PCT Process)(Bias Resistor built-in Transistor)

# RN1114MFV to RN1118MFV

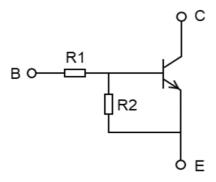
### 1. Applications

- · Switching
- · Inverter Circuits
- · Interfacing
- · Driver Circuits

#### 2. Features

- (1) Ultra-small package, suited to very high density mounting
- (2) The integrated bias resistor reduces the number of external parts required, making it possible to reduce system size and assembly time.
- (3) Toshiba offers transistors with a wide range of resistance to accommodate various circuit designs.
- (4) Complementary to RN2114MFV to 2118MFV

#### 3. Equivalent Circuit

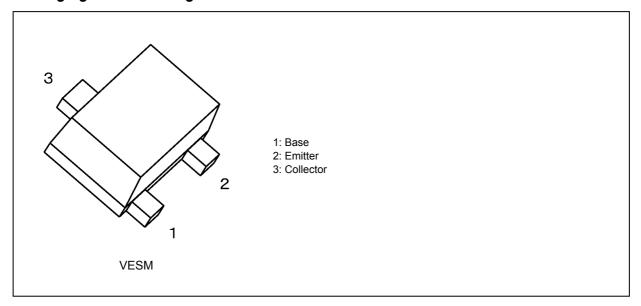


#### 4. Bias Resistor Values

Part No.	R1 (kΩ)	R2 (kΩ)
RN1114MFV	1	10
RN1115MFV	2.2	10
RN1116MFV	4.7	10
RN1117MFV	10	4.7
RN1118MFV	47	10



### 5. Packaging and Pin Assignment



### 6. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Rating	Unit	
Collector-base voltage	RN1114MFV to RN1118MFV	V <sub>CBO</sub>	50	V
Collector-emitter voltage	RN1114MFV to RN1118MFV	V <sub>CEO</sub>	50	V
Emitter-base voltage	RN1114MFV	V <sub>EBO</sub>	5	V
	RN1115MFV		6	
	RN1116MFV		7	
	RN1117MFV		15	
	RN1118MFV		25	
Collector current	RN1114MFV to RN1118MFV	I <sub>C</sub>	100	mA
Collector power dissipation	RN1114MFV to RN1118MFV	P <sub>C</sub> (Note 1)	150	mW
Junction temperature	RN1114MFV to RN1118MFV	T <sub>j</sub>	150	°C
Storage temperature	RN1114MFV to RN1118MFV	T <sub>stg</sub>	-55 to 150	°C

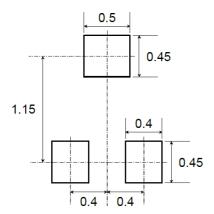
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on an FR4 board (25.4 mm  $\times$  25.4 mm  $\times$  1.6 mm)



### 7. Land Pattern Dimensions (for reference only)



Unit: mm



# 8. Electrical Characteristics (Unless otherwise specified, $T_a$ = 25 °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off current	RN1114MFV to	I <sub>CBO</sub>	V <sub>CB</sub> = 50 V, I <sub>E</sub> = 0 mA	_	_	100	nA
	RN1118MFV	I <sub>CEO</sub>	V <sub>CE</sub> = 50 V, I <sub>B</sub> = 0 mA	_	_	500	
Emitter cut-off current	RN1114MFV	I <sub>EBO</sub>	$V_{EB} = 5 \text{ V}, I_{C} = 0 \text{ mA}$	0.35	_	0.65	mA
	RN1115MFV		V <sub>EB</sub> = 6 V, I <sub>C</sub> = 0 mA	0.37	_	0.71	
	RN1116MFV		$V_{EB} = 7 \text{ V, } I_{C} = 0 \text{ mA}$	0.36	_	0.68	
	RN1117MFV		$V_{EB}$ = 15 V, $I_{C}$ = 0 mA	0.78		1.46	
	RN1118MFV		$V_{EB}$ = 25 V, $I_C$ = 0 mA	0.33		0.63	
DC current gain	RN1114MFV to RN1116MFV, RN1118MFV	h <sub>FE</sub>	$V_{CE}$ = 5 V, $I_{C}$ = 10 mA	50		_	_
	RN1117MFV			30	_	_	
Collector-emitter saturation voltage	RN1114MFV to RN1118MFV	V <sub>CE(sat)</sub>	I <sub>C</sub> = 5 mA, I <sub>B</sub> = 0.5 mA	_	0.1	0.3	V
Input voltage (ON)	RN1114MFV	$V_{I(ON)}$	$V_{CE} = 0.2 \text{ V}, I_{C} = 5 \text{ mA}$	0.6	_	2.0	V
	RN1115MFV			0.7		2.5	
	RN1116MFV			8.0	_	2.5	
	RN1117MFV			1.5	_	3.5	
	RN1118MFV			2.5	_	10.0	
Input voltage (OFF)	RN1114MFV	$V_{I(OFF)}$	$V_{CE} = 5 \text{ V}, I_{C} = 0.1 \text{ mA}$	0.3	_	0.9	V
	RN1115MFV			0.3	_	1.0	
	RN1116MFV			0.3	_	1.1	
	RN1117MFV			0.3		2.3	
	RN1118MFV			0.5	_	5.7	
Collector output capacitance	RN1114MFV to RN1118MFV	C <sub>ob</sub>	V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0 A, f = 1 MHz	_	0.7	_	pF
Input resistance	RN1114MFV	R <sub>1</sub>	_	0.7	1.0	1.3	kΩ
	RN1115MFV			1.54	2.2	2.86	
	RN1116MFV			3.29	4.7	6.11	
	RN1117MFV			7	10	13	
	RN1118MFV			32.9	47	61.1	
Resistor ratio	RN1114MFV	R1/R2	_	_	0.1	_	_
	RN1115MFV			_	0.22	_	
	RN1116MFV			_	0.47		
	RN1117MFV			_	2.13	_	
	RN1118MFV			_	4.7	_	



### 9. Marking

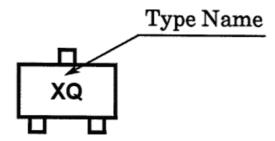


Fig. 9.1 Marking RN1114MFV

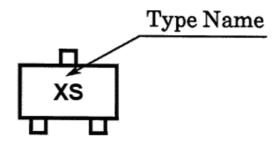


Fig. 9.2 Marking RN1115MFV

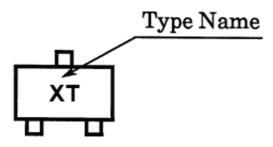


Fig. 9.3 Marking RN1116MFV

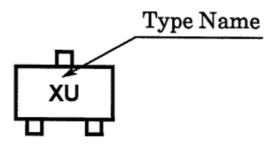


Fig. 9.4 Marking RN1117MFV

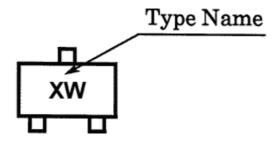


Fig. 9.5 Marking RN1118MFV

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### 10. Characteristics Curves (Note)

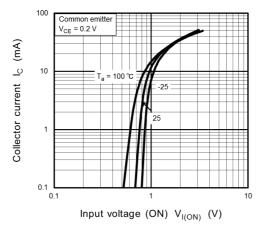


Fig. 10.1 RN1114MFV I<sub>C</sub>-V<sub>I(ON)</sub>

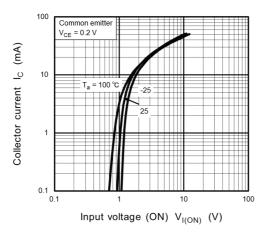


Fig. 10.3 RN1116MFV I<sub>C</sub>-V<sub>I(ON)</sub>

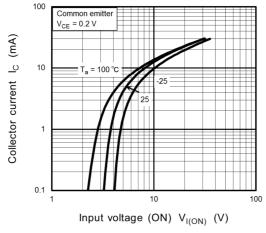


Fig. 10.5 RN1118MFV I<sub>C</sub>-V<sub>I(ON)</sub>

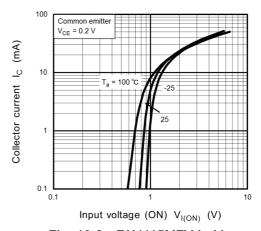


Fig. 10.2 RN1115MFV I<sub>C</sub>-V<sub>I(ON)</sub>

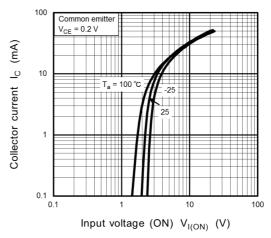


Fig. 10.4 RN1117MFV I<sub>C</sub>-V<sub>I(ON)</sub>



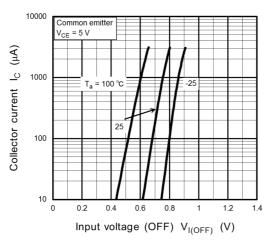


Fig. 10.6 RN1114MFV I<sub>C</sub>-V<sub>I(OFF)</sub>

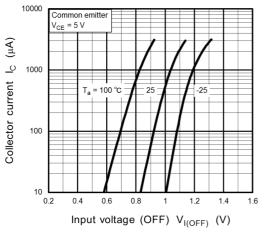


Fig. 10.8 RN1116MFV I<sub>C</sub>-V<sub>I(OFF)</sub>

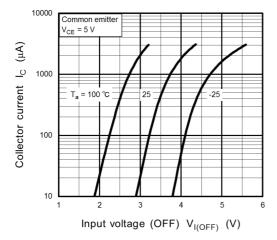


Fig. 10.10 RN1118MFV I<sub>C</sub>-V<sub>I(OFF)</sub>

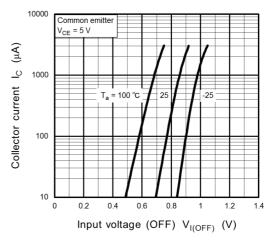


Fig. 10.7 RN1115MFV I<sub>C</sub>-V<sub>I(OFF)</sub>

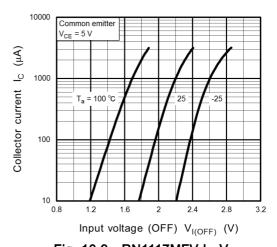


Fig. 10.9 RN1117MFV I<sub>C</sub>-V<sub>I(OFF)</sub>



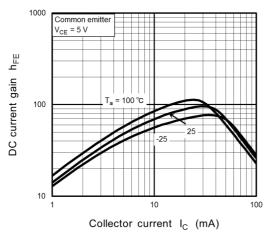


Fig. 10.11 RN1114MFV hFE-IC

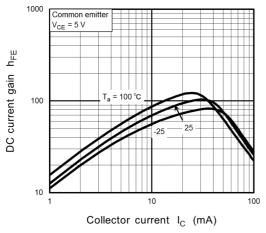


Fig. 10.13 RN1116MFV hFE-IC

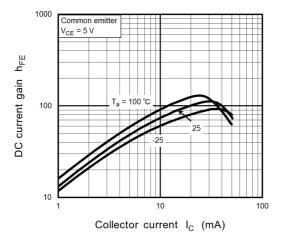


Fig. 10.15 RN1118MFV hFE-IC

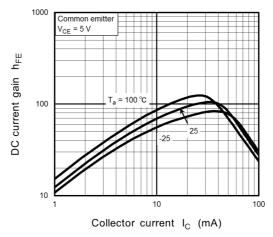


Fig. 10.12 RN1115MFV hFE-IC

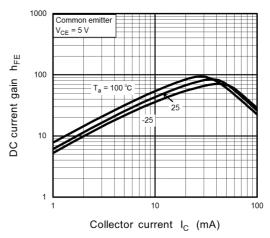


Fig. 10.14 RN1117MFV hFE-IC



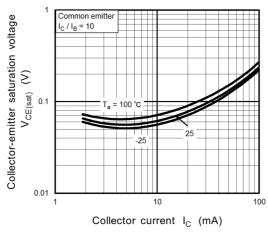


Fig. 10.16 RN1114MFV V<sub>CE(sat)</sub>-I<sub>C</sub>

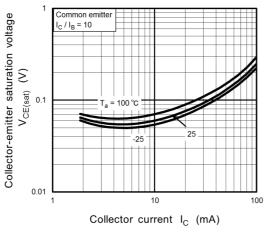


Fig. 10.18 RN1116MFV V<sub>CE(sat)</sub>-I<sub>C</sub>

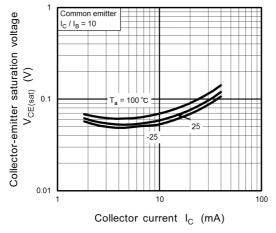


Fig. 10.20 RN1118MFV  $V_{CE(sat)}$ -I<sub>C</sub>

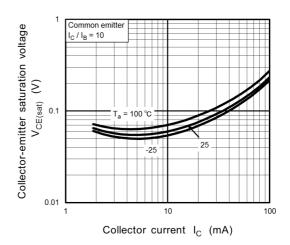


Fig. 10.17 RN1115MFV V<sub>CE(sat)</sub>-I<sub>C</sub>

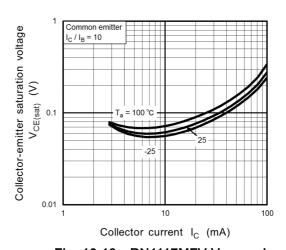


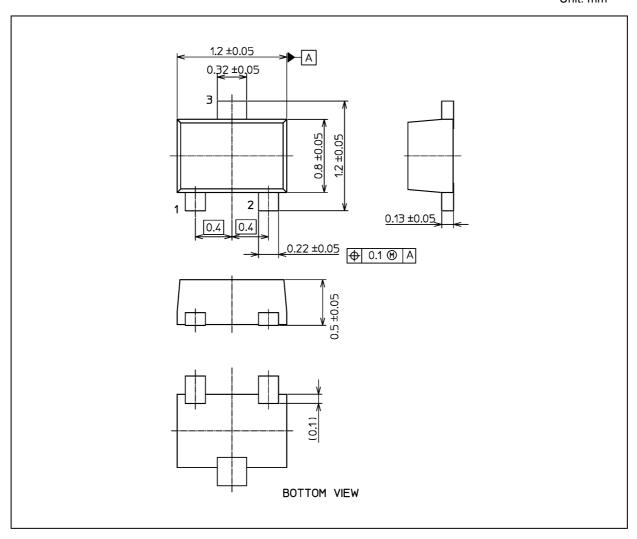
Fig. 10.19 RN1117MFV V<sub>CE(sat)</sub>-I<sub>C</sub>

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



### **Package Dimensions**

Unit: mm



Weight: 1.5 mg (typ.)

	Package Name(s)
TOSHIBA: 1-1Q1S	
Nickname: VESM	



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